Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-03-11
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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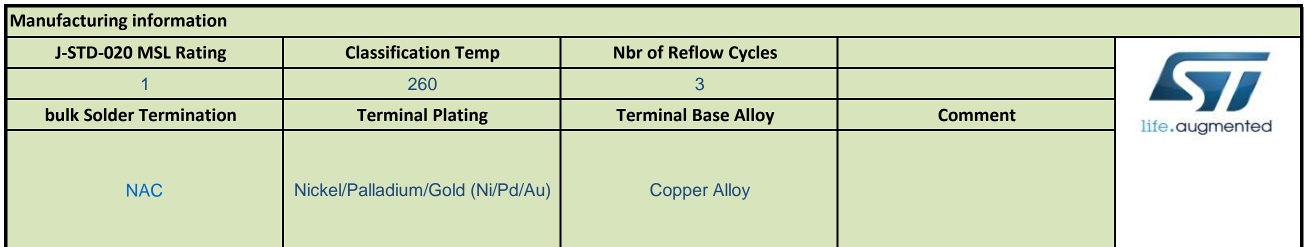
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M93C56-RMN3TP/K	PGO7*0C561KN	A	3068	2017-03-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SON	STDJEDEC	8	Gull Wing	
Comment	Package : O7 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-12th January 2017	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**TRUE**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**PGO7*0C561KN**				7000000.0	999999.0
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	0.511	mg	supplier	die	Silicon (Si)	7440-21-3		0.492	mg	962818	6150
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3914	25
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1957	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	31311	200
Lead-frame	M-011 Other inorganic materials	24.984	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.347	mg	974500	304339
				supplier	alloy	Iron (Fe)	7439-89-6		0.586	mg	23460	7327
				supplier	alloy	Zinc (Zn)	7440-66-6		0.030	mg	1200	375
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.021	mg	840	262
Lead-frame Coating	M-011 Other inorganic materials	0.124	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	916800	1425
				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	58700	91
				supplier	coating	Gold (Au)	7440-57-5		0.003	mg	24500	38
Die Attach	M-011 Other inorganic materials	1.027	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.925	mg	900000	11557
				supplier	glue or soft solder	acrylate	Proprietary		0.062	mg	60000	770
				supplier	glue or soft solder	Methacrylate	Proprietary		0.039	mg	38000	488
				supplier	glue or soft solder	acrylate	Proprietary		0.002	mg	2000	26
Wires	M-011 Other inorganic materials	0.062	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.062	mg	1000000	776
Encapsulation	M-011 Other inorganic materials	53.290	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		3.938	mg	73900	49226
				supplier	Moulding Compound	Phenol Resin	Proprietary		2.625	mg	49266	32818
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		46.254	mg	867966	578171
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.263	mg	4927	3282
				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.210	mg	3941	2625
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	916800	14
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0